Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2542

### **Switching Regulator Applications**

• 4-V gate drive

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & :\ RDS\ (ON) = 0.75\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & :\ |\ Y_{fs}| = 7.0\ S\ (typ.) \\ \bullet & Low\ leakage\ current & :\ IDSS = 100\ \mu A\ (max)\ (VDS = 500\ V) \\ \bullet & Enhancement\ mode & :\ V_{th} = 2.0{\sim}4.0\ V\ (VDS = 10\ V,\ ID = 1\ mA) \end{array}$ 

### Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	500	V
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	500	V
Gate-source voltage		V <sub>GSS</sub>	±30	V
Drain current	DC (Note 1)	I <sub>D</sub>	8	Α
	Pulse (Note 1)	I <sub>DP</sub>	32	Α
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	80	W
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	312	mJ
Avalanche current		I <sub>AR</sub>	8	Α
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	8	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	-55~150	°C

10.3MAX. 63.6±0.2

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10.3MAX. 70.76

Weight: 2.0 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.56	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 8.3 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 8 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



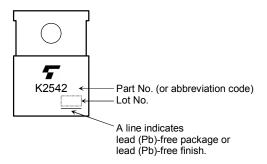
## **Electrical Characteristics (Ta = 25°C)**

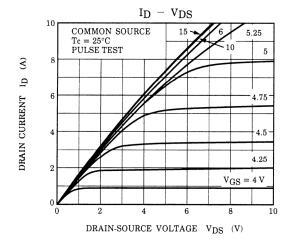
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V <sub>(BR) GSS</sub>	$I_{G}$ = ±10 $\mu$ A, $V_{GS}$ = 0 $V$	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>DS</sub> = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	_	_	V
Gate threshold v	oltage/	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A	_	0.75	0.85	Ω
Forward transfer	r admittance	Y <sub>fs </sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 A	3.5	7.0	_	S
Input capacitano	e	C <sub>iss</sub>		_	1300	_	
Reverse transfe	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		C <sub>oss</sub>	] [	_	400	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{OV}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$	_	26	_	
	Turn-on time	t <sub>on</sub>		_	45	ı	ns
	Fall time	t <sub>f</sub>		_	40	_	115
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	_	140	_	
Total gate charge (Gate-source plus gate-drain)		$Q_{g}$		_	30	_	
Gate-source charge		$Q_{gs}$	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$		17	_	nC
Gate-drain ("miller") charge		$Q_{gd}$			13	_	

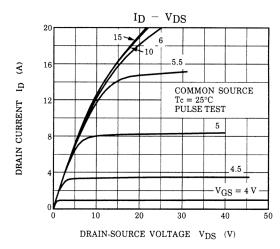
## Source-Drain Ratings and Characteristics (Ta = 25°C)

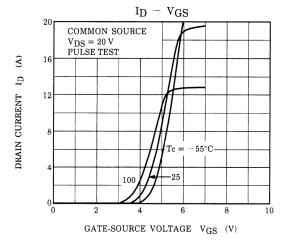
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	-	8	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	32	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V dI <sub>DR</sub> / dt = 100 A / μs		1200		ns
Reverse recovery charge	Qrr	dl <sub>DR</sub> / dt = 100 A / μs	- 1	10		μC

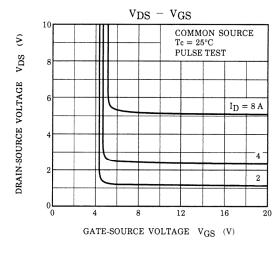
### Marking

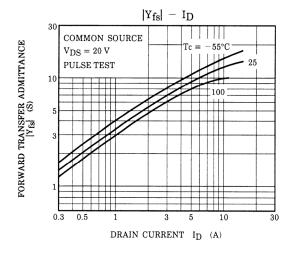


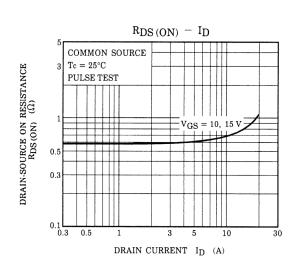


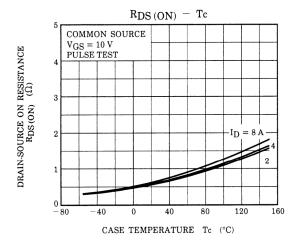


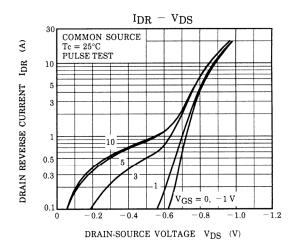


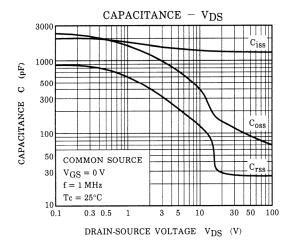


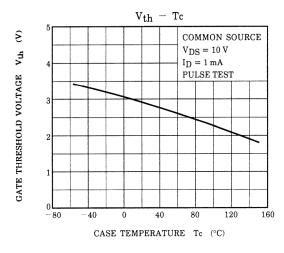


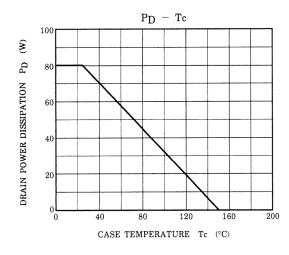


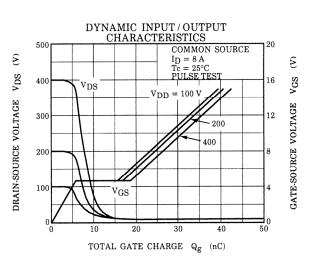




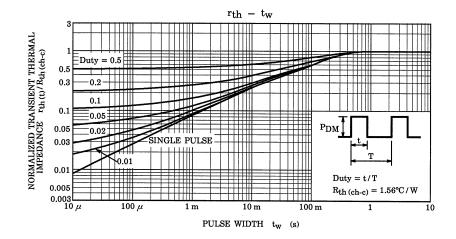


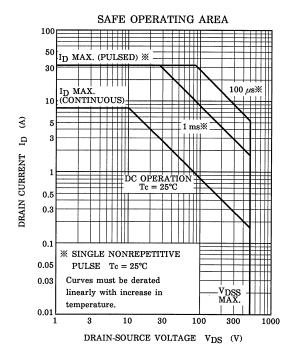


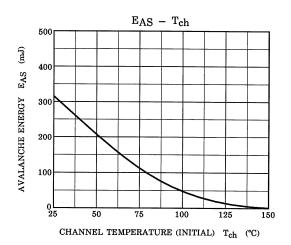


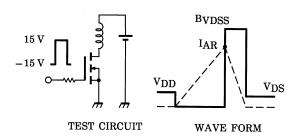


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$$R_G = 25 \Omega$$
  
 $V_{DD} = 90 \text{ V}, L = 8.3 \text{ mH}$   $EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{B}{BVD}\right)$ 

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